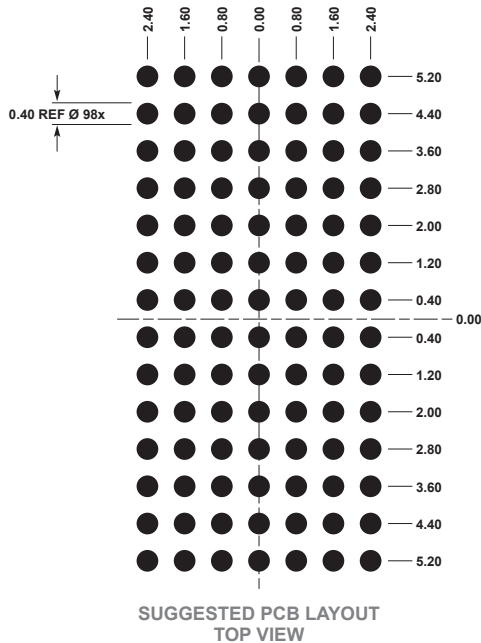
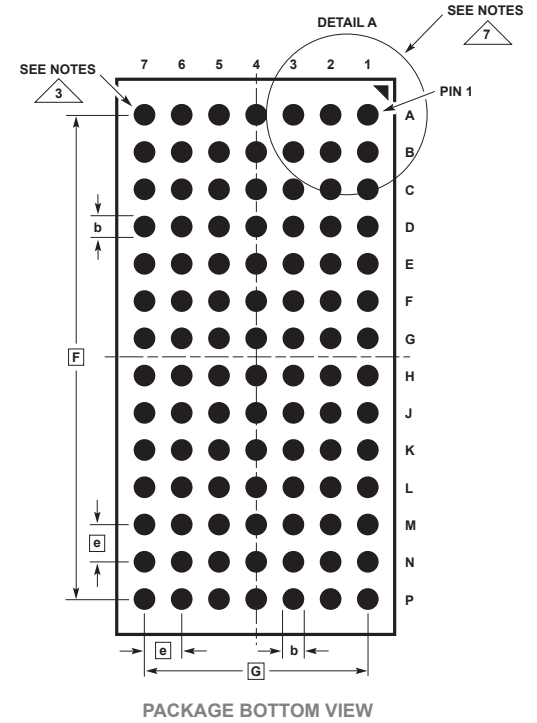
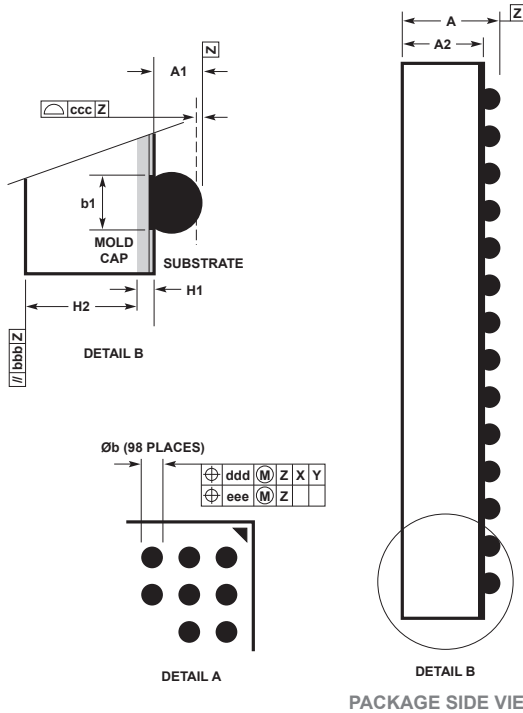
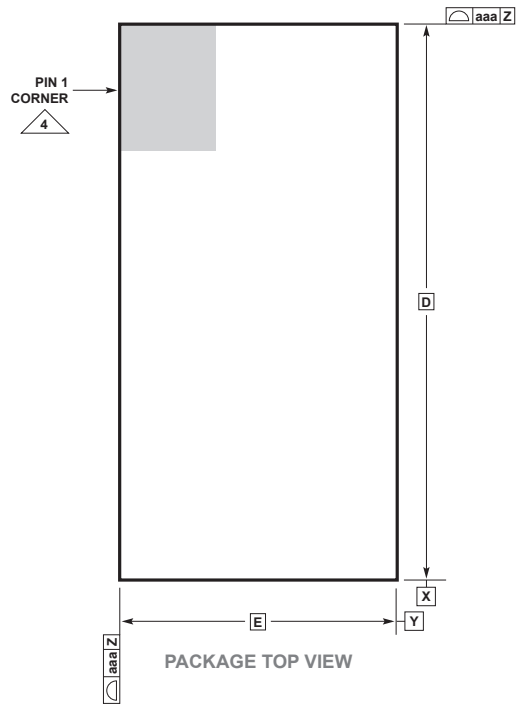


BGA Package
98-Lead (6mm × 12mm × 1.92mm)
 (Reference LTC DWG # 05-08-7090 Rev Ø)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.73	1.92	2.11	
A1	0.30	0.40	0.50	BALL HT
A2	1.43	1.52	1.61	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D	12.00			
E	6.00			
e	0.80			
F	10.40			
G	4.80			
H1	0.32 REF			SUBSTRATE THK
H2	1.20 REF			MOLD CAP HT
aaa			0.15	
bbb			0.10	
ddd			0.15	
eee			0.08	
TOTAL NUMBER OF BALLS: 98				

- NOTES:**
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING NOT TO SCALE
 - 3 BALL DESIGNATION PER JEP95
 - 4 DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 - 6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

